



CYPRESS

CY2CC810**1:10 Clock Fanout Buffer****Features**

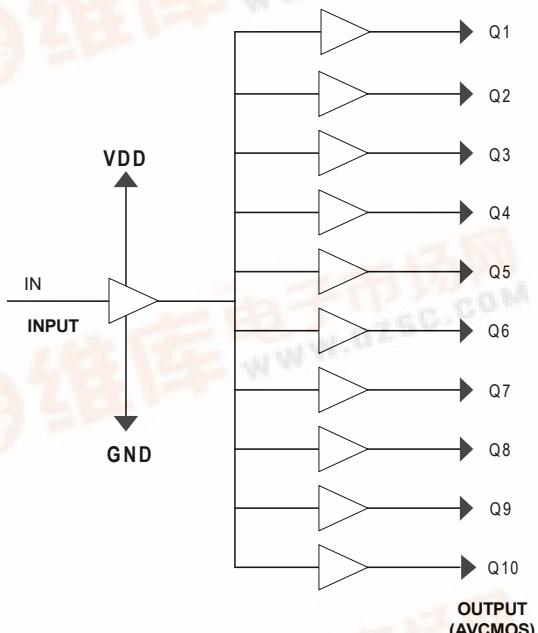
- Low-voltage operation
- V_{DD} range from 2.5V to 3.3V
- 1:10 fanout
- Over voltage tolerant input hot swappable
- Drives either a 50-Ohm or 75-Ohm transmission line
- Low-input capacitance
- 250 ps typical output-to-output skew
- 19 ps typical DJ jitter
- Typical propagation delay < 3.5ns
- High-speed operation > 500 MHz
- Industrial versions available
- Available packages include: SOIC, SSOP

Description

The Cypress series of network circuits are produced using advanced 0.35-micron CMOS technology, achieving the industry's fastest logic and buffers.

The Cypress CY2CC810 fanout buffer features one input and ten outputs. Designed for data communications clock management applications, the large fanout from a single input reduces loading on the input clock.

AVCMOS-type outputs dynamically adjust for variable impedance matching and reduce noise overall.

Block Diagram**Pin Configuration**

CY2CC810	20	VDD
IN	1	Q10
GND	2	Q9
Q1	3	GND
VDD	4	Q8
Q2	5	VDD
GND	6	Q7
Q3	7	GND
VDD	8	Q6
Q4	9	Q5
GND	10	

20 pin SOIC/SSOP

Pin Description

Pin Number	Pin Name	Description	
1	IN	Input	LVC MOS
2, 6, 10, 13, 17	GND	Ground	Power
4, 8, 15, 20	V_{DD}	Power Supply	Power
3, 5, 7, 9, 11, 12, 14, 16, 18, 19	Q1... Q10	Output	AVCMOS

Maximum Ratings^[1, 2]

Storage Temperature:	-65°C to + 150°C	Supply Voltage to Ground Potential
Ambient Temperature:	-40°C to +85°C	(Outputs only) -0.5V to V _{DD} + 1V
Supply Voltage to Ground Potential			DC Output Voltage -0.5V to V _{DD} + 1V
V _{CC}	-0.5V to 4.6V	Power Dissipation 0.75W
Input	-0.5V to 5.8V	

DC Electrical Characteristics @ 3.3V (see Figure 5)

Parameter	Description	Conditions		Min.	Typ.	Max.	Unit
V _{OH}	Output High Voltage	V _{DD} = Min., V _{IN} = V _{IH} or V _{IL}	I _{OH} = -12 mA	2.3	3.3		V
V _{OL}	Output Low Voltage	V _{DD} = Min., V _{IN} = V _{IH} or V _{IL}	I _{OL} = 12 mA		0.2	0.5	V
V _{IH}	Input High Voltage	Guaranteed Logic High Level		2		5.8	V
V _{IL}	Input Low Voltage	Guaranteed Logic Low Level				0.8	V
I _{IH}	Input High Current	V _{DD} = Max.	V _{IN} = 2.7V			1	µA
I _{IL}	Input Low Current	V _{DD} = Max.	V _{IN} = 0.5V			-1	µA
I _I	Input High Current	V _{DD} = Max., V _{IN} = V _{DD} (Max.)				20	µA
V _{IK}	Clamp Diode Voltage	V _{DD} = Min., I _{IN} = -18 mA			-0.7	-1.2	V
I _{OK}	Continuous Clamp Current	V _{DD} = Max., V _{OUT} = GND				-50	mA
O _{OFF}	Power-down Disable	V _{DD} = GND, V _{OUT} = < 4.5V				100	µA
V _H	Input Hysteresis	V _{DD} = Min., V _{IN} = V _{IH} or V _{IL}			80		mV

DC Electrical Characteristics @ 2.5V (see Figure 1)

Parameter	Description	Conditions		Min.	Typ.	Max.	Unit
V _{OH}	Output High Voltage	V _{DD} = Min., V _{IN} = V _{IH} or V _{IL}	I _{OH} = -7 mA	1.8			V
			I _{OH} = 12 mA	1.6			V
V _{OL}	Output Low Voltage	V _{DD} = Min., V _{IN} = V _{IH} or V _{IL}	I _{OL} = 12 mA			0.65	V
V _{IH}	Input High Voltage	Guaranteed Logic High Level		1.6		5.0	V
V _{IL}	Input Low Voltage	Guaranteed Logic Low Level				0.8	V
I _{IH}	Input High Current	V _{DD} = Max.	V _{IN} = 2.4V			1	µA
I _{IL}	Input Low Current	V _{DD} = Max.	V _{IN} = 0.5V			-1	µA
I _I	Input High Current	V _{DD} = Max., V _{IN} = V _{DD} (Max.)				20	µA
V _{IK}	Clamp Diode Voltage	V _{DD} = Min., I _{IN} = -18 mA			-0.7	-1.2	V
I _{OK}	Continuous Clamp Current	V _{DD} = Max., V _{OUT} = GND				-50	mA
O _{OFF}	Power-down Disable	V _{DD} = GND, V _{OUT} = < 4.5V				100	µA
V _H	Input Hysteresis				80		mV

Capacitance

Parameter	Description	Test Conditions	Min.	Typ.	Max.	Unit
C _{in}	Input Capacitance	V _{IN} = 0V		2.5		pF
C _{out}	Output Capacitance	V _{OUT} = 0V		6.5		pF

Notes:

1. Stresses greater than those listed under absolute maximum ratings may cause permanent damage to the device. This is intended to be a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. Multiple Supplies: The voltage on any input or I/O pin cannot exceed the power pin during power-up. Power supply sequencing is NOT required.

Power Supply Characteristics (see *Figure 5*)

Parameter	Description	Test Conditions	Min.	Typ.	Max.	Unit
ΔI_{CC}	Delta I_{CC} Quiescent Power Supply Current	$(I_{DD} @ V_{DD} = \text{Max. and } V_{IN} = V_{DD}) - (I_{DD} @ V_{DD} = \text{Max. and } V_{IN} = V_{DD} - 0.6V)$			50	μA
I_{CCD}	Dynamic Power Supply Current	$V_{DD} = \text{Max.}$ Input toggling 50% Duty Cycle, Outputs Open			0.63	mA/ MHz
I_C	Total Power Supply Current	$V_{DD} = \text{Max.}$ Input toggling 50% Duty Cycle, Outputs Open $f_L = 40 \text{ MHz}$			25	mA

High-frequency Parametrics

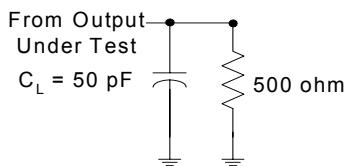
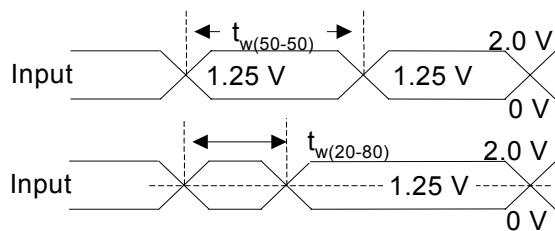
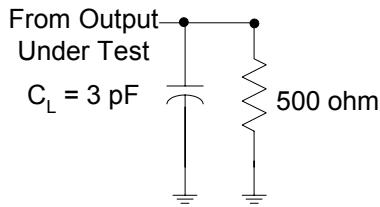
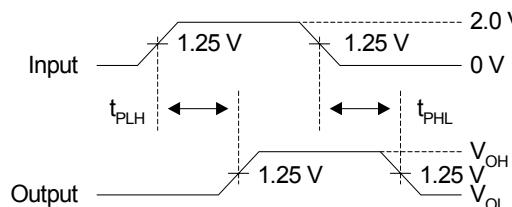
Parameter	Description	Test Conditions	Min.	Typ.	Max.	Unit
D_J	Jitter, Deterministic	50% duty cycle $t_W(50-50)$ The "point to point load circuit" Output Jitter – Input Jitter	2.5V		23	35
			3.3V		19	30
F_{max}	Maximum frequency $V_{DD} = 3.3V$	50% duty cycle $t_W(50-50)$ Standard Load Circuit.	See <i>Figure 5</i>		160	MHz
		50% duty cycle $t_W(50-50)$ The "point to point load circuit"	See <i>Figure 7</i>		650	
F_{max} 2.5V	Maximum frequency $V_{DD} = 2.5 \text{ V}$	The "point to point load circuit" $V_{IN} = 2.4V/0.0V$ $V_{OUT} = 1.7V/0.7V$	See <i>Figure 7</i>		200	MHz
$F_{max}(20)$	Maximum frequency $V_{DD} = 3.3 \text{ V}$	20% duty cycle $t_W(20-80)$ The "point to point load circuit" $V_{IN} = 3.0V/0.0V$ $V_{OUT} = 2.3V/0.4V$	See <i>Figure 7</i>		250	MHz
		The "point to point load circuit" $V_{IN} = 2.4V/0.0V$ $V_{OUT} = 1.7V/0.7V$	See <i>Figure 3</i>		200	MHz
t_W	Minimum pulse $V_{DD} = 3.3 \text{ V}$	The "point to point load circuit" $V_{IN} = 3.0V/0.0V$ $F = 100 \text{ MHz}$ $V_{OUT} = 2.0V/0.8V$	See <i>Figure 7</i>	1		ns
	Minimum pulse $V_{DD} = 2.5 \text{ V}$	The "point to point load circuit" $V_{IN} = 2.4V/0.0V$ $F = 100 \text{ MHz}$ $V_{OUT} = 1.7V/0.7V$	See <i>Figure 3</i>	1		

AC Switching Characteristics @ 3.3V $V_{DD} = 3.3V \pm 5\%$, Temperature = -40°C to $+85^\circ\text{C}$

Parameter	Description		Min.	Typ.	Max.	Unit
t_{PLH}	Propagation Delay – Low to High	See <i>Figure 4</i>	1.5	2.7	3.5	ns
t_{PHL}	Propagation Delay – High to Low		1.5	2.7	3.5	ns
t_R	Output Rise Time			0.8		V/ns
t_F	Output Fall Time			0.8		V/ns
$t_{SK(0)}$	Output Skew: Skew between outputs of the same package (in phase)	See <i>Figure 10</i>		0.25	0.38	ns
$t_{SK(p)}$	Pulse Skew: Skew between opposite transitions of the same output ($t_{PHL} - t_{PLH}$).	See <i>Figure 9</i>			0.2	ns
$t_{SK(t)}$	Package Skew: Skew between outputs of different packages at the same power supply voltage, temperature and package type.	See <i>Figure 11</i>			0.42	ns

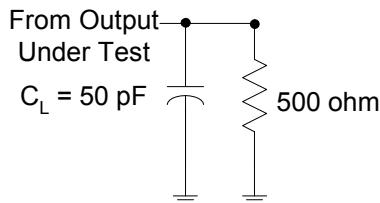
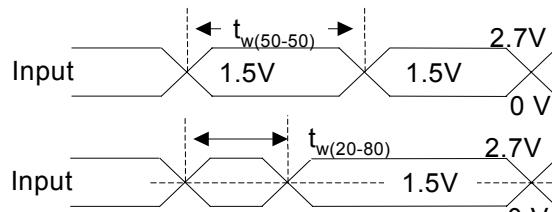
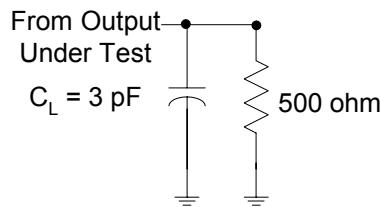
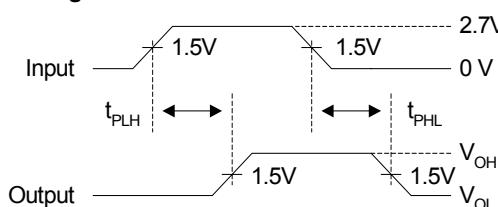
AC Switching Characteristics @ 2.5V $V_{DD} = 2.5V \pm 5\%$, Temperature = -40°C to $+85^{\circ}\text{C}$

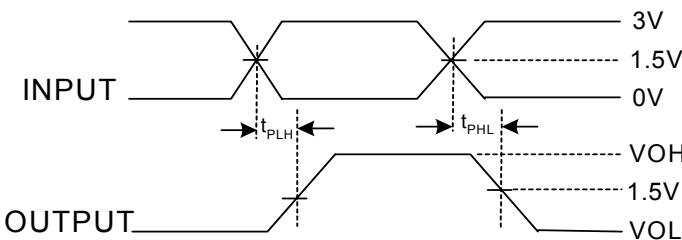
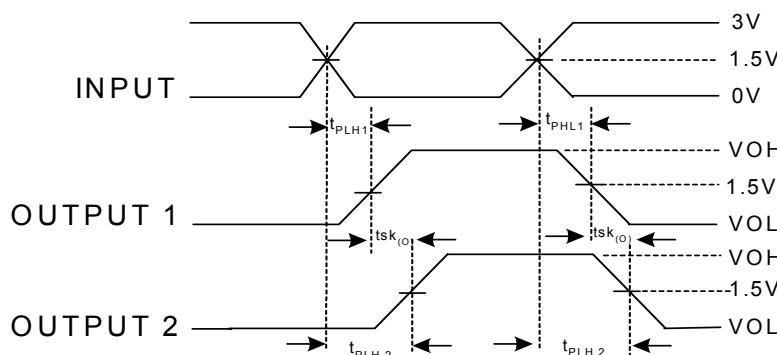
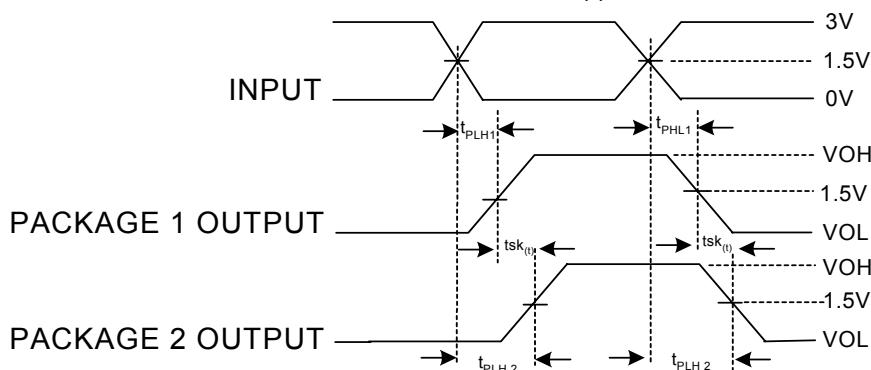
Parameter	Description	Min.	Typ.	Max.	Unit
t_{PLH}	Propagation Delay – Low to High	See Figure 4	1.5	2.0	3.5 ns
t_{PHL}	Propagation Delay – High to Low		1.5	2.0	3.5 ns
t_R	Output Rise Time			0.8	V/ns
t_F	Output Fall Time			0.8	V/ns
$t_{SK(0)}$	Output Skew: Skew between outputs of the same package (in phase)	See Figure 10	0.25	0.38	ns
$t_{SK(p)}$	Pulse Skew: Skew between opposite transitions of the same output ($t_{PHL} - t_{PLH}$).	See Figure 9		0.4	ns
$t_{SK(t)}$	Package Skew: Skew between outputs of different packages at the same power supply voltage, temperature and package type.	See Figure 11		0.65	ns

**Parameter Measurement Information:
 $V_{DD} @ 2.5V$**

Figure 1. Load Circuit [3,4,5]

Figure 2. Voltage Waveforms–Pulse Duration [6]

Figure 3. Point to Point Load Circuit [3,4,5]

Figure 4. Voltage Waveforms–Propagation Delay Times [4]

Notes:

3. C_L includes probe and jig capacitance.
4. All input pulses are supplied by generators having the following characteristics: PRR < 100 MHz, $Z_0 = 50\text{W}$, $t_R < 2.5\text{nS}$, $t_F < 2.5\text{nS}$.
5. The outputs are measured one at a time with one transition per measurement.
6. T_{PLH} and T_{PHL} are the same as t_{pd} .

**Parameter Measurement Information:
 $V_{DD} @ 3.3V$**

Figure 5. Load Circuit [3,4,5]

Figure 6. Voltage Waveforms–Pulse Duration [6]

Figure 7. Point to Point Load Circuit [3,4,5]

Figure 8. Voltage Waveforms–Propagation Delay Times [4]


Figure 9. Pulse Skew- $tsk_{(p)}$

Figure 10. Output Skew- $tsk_{(0)}$

Figure 11. Package Skew- $tsk_{(t)}$

Ordering Information

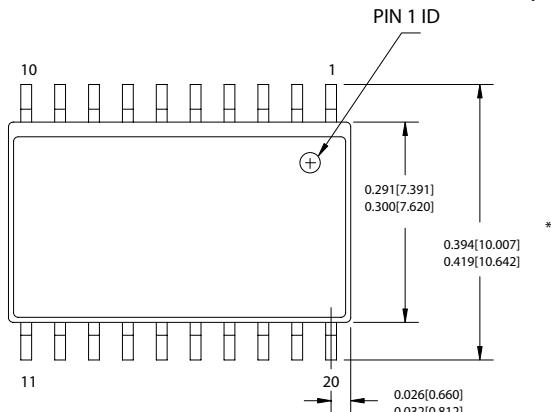
Part Number	Package Type	Product Flow
CY2CC810OI	20-pin SSOP	Industrial, -40°C to 85°C
CY2CC810OIT	20-pin SSOP-Tape and Reel	Industrial, -40°C to 85°C
CY2CC810OC	20-pin SSOP	Commercial, 0°C to 70°C
CY2CC810OCT	20-pin SSOP-Tape and Reel	Commercial, 0°C to 70°C
Lead-free		
CY2CC810OXC	20-pin SSOP	Commercial, 0°C to 70°C
CY2CC810OXCT	20-pin SSOP-Tape and Reel	Commercial, 0°C to 70°C
CY2CC810OXI	20-pin SSOP	Industrial, -40°C to 85°C
CY2CC810OXIT	20-pin SSOP-Tape and Reel	Industrial, -40°C to 85°C



CY2CC810

Package Drawing and Dimensions

20-Lead (300-Mil) SOIC S5

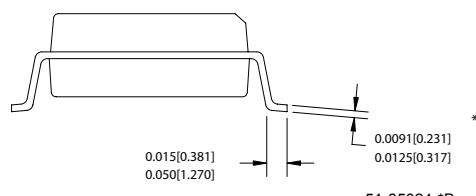
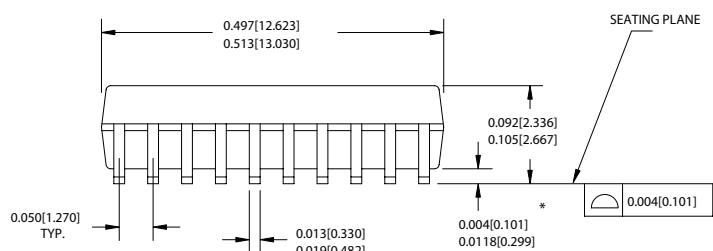


DIMENSIONS IN INCHES [MM] MIN.
MAX

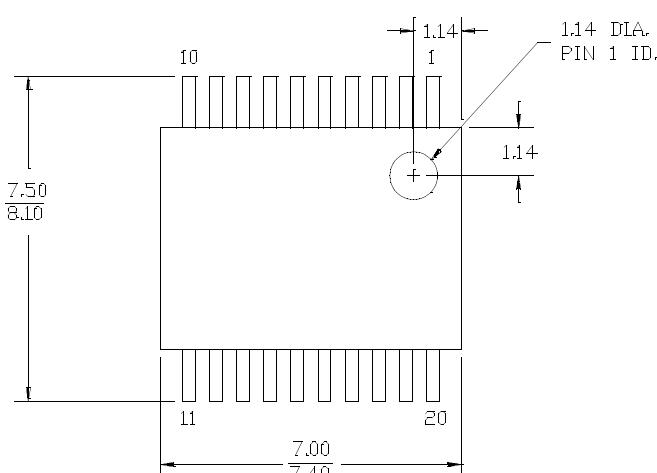
REFERENCE JEDEC MO-119

PACKAGE WEIGHT 0.55 gms

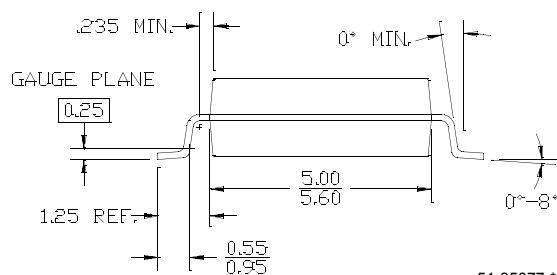
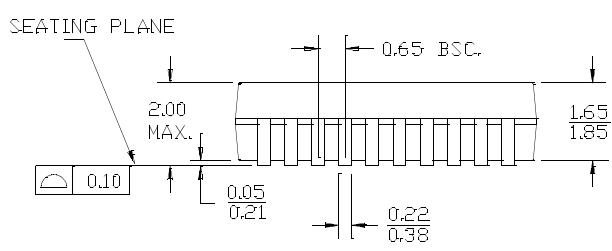
PART #	
S20.3	STANDARD PKG.
SZ20.3	LEAD FREE PKG.



20-lead (5.3-mm) Shrunk Small Outline Package Q20



DIMENSIONS IN MILLIMETERS MIN. MAX.



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CY2CC810

Document History Page

Document Title: CY2CC810 1:10 Clock Fanout Buffer Document #: 38-07056				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	107081	06/07/01	IKA	Convert from IMI to Cypress
*A	114315	05/09/02	TSM	ΔI_{DD} Validation
*B	119117	10/07/02	RGL	Added 5.8 as the Max. value of V_{IH} in the DC Electrical Characteristics @3.3V table. Changed the Max. value of V_{IH} from 1.8 to 5.0 in the DC Electrical Characteristics @2.5V table.
*C	122743	12/14/02	RBI	Added power up requirements to maximum ratings information.
*D	387761	See ECN	RGL	Added typical values Updated jitter and skew specs. Removed devices with SOIC package Added Lead-free SSOP package



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